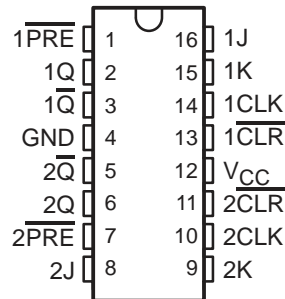


74ACT11112 DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOP WITH CLEAR AND PRESET

SCAS064A – D3339, JUNE 1989 – REVISED APRIL 1993

- Inputs Are TTL-Voltage Compatible
- Fully Buffered to Offer Maximum Isolation From External Disturbance
- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1- μ m Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline Packages and Standard Plastic 300-mil DIPs

D OR N PACKAGE
(TOP VIEW)



description

This device contains two independent J-K negative-edge-triggered flip-flops. A low level at the \overline{PRE} or \overline{CLR} input sets or resets the outputs regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the J and K inputs meeting the setup time requirements are transferred to the outputs on the negative-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the fall time of the clock pulse. Following the hold-time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by tying J and K high.

The 74ACT11112 is characterized for operation from – 40°C to 85°C.

FUNCTION TABLE

| INPUTS | | | | | OUTPUTS | |
|------------------|------------------|-----|---|---|----------------|------------------|
| \overline{PRE} | \overline{CLR} | CLK | J | K | Q | \overline{Q} |
| L | H | X | X | X | H | L |
| H | L | X | X | X | L | H |
| L | L | X | X | X | H [†] | H [†] |
| H | H | ↓ | L | L | Q ₀ | \overline{Q}_0 |
| H | H | ↓ | H | L | H | L |
| H | H | ↓ | L | H | L | H |
| H | H | ↓ | H | H | TOGGLE | TOGGLE |
| H | H | H | X | X | Q ₀ | \overline{Q}_0 |

† This configuration is nonstable; that is, it will not persist when either \overline{PRE} or \overline{CLR} returns to the inactive (high) level.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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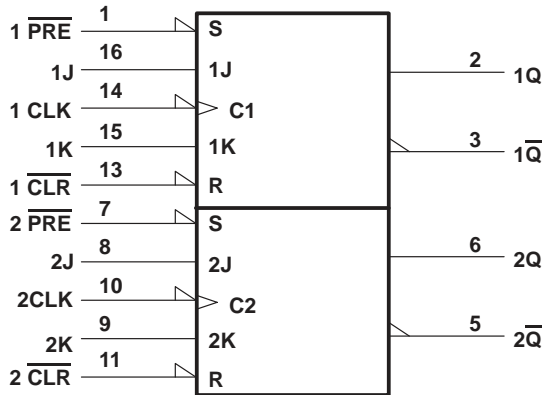
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74ACT11112

DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOP WITH CLEAR AND PRESET

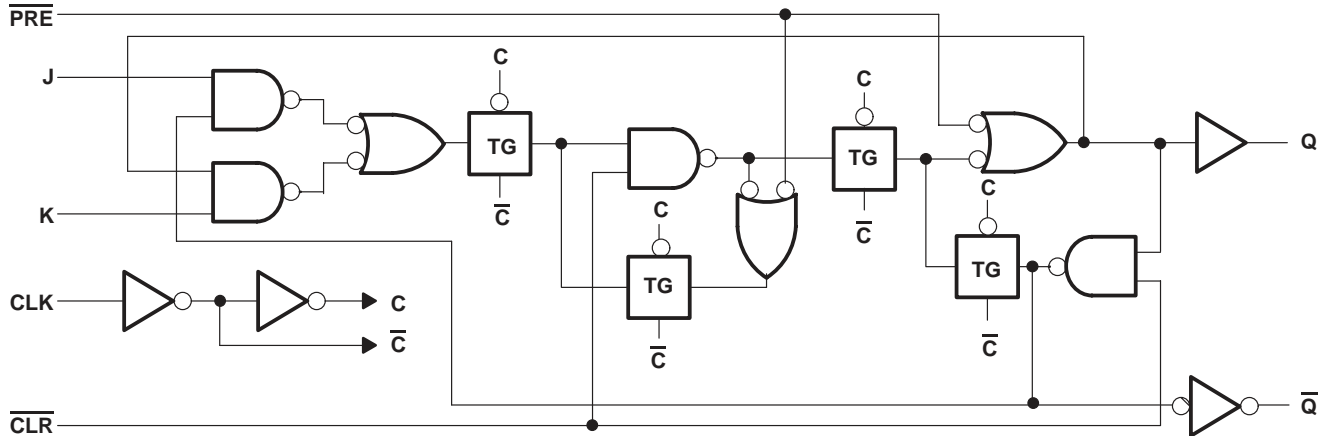
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-42.

logic diagram, each flip-flop (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

| | |
|--|----------------------------|
| Supply voltage range, V_{CC} | -0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | -0.5 V to $V_{CC} + 0.5$ V |
| Output voltage range, V_O (see Note 1) | -0.5 V to $V_{CC} + 0.5$ V |
| Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) | ± 20 mA |
| Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) | ± 50 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | ± 50 mA |
| Continuous current through V_{CC} or GND | ± 100 mA |
| Storage temperature range | -65°C to 150°C |

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOP WITH CLEAR AND PRESET

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recommended operating conditions

| | | MIN | MAX | UNIT |
|---------------------|------------------------------------|-----|----------|------|
| V_{CC} | Supply voltage | 4.5 | 5.5 | V |
| V_{IH} | High-level input voltage | 2 | | V |
| V_{IL} | Low-level input voltage | | 0.8 | V |
| V_I | Input voltage | 0 | V_{CC} | V |
| V_O | Output voltage | 0 | V_{CC} | V |
| I_{OH} | High-level output current | | -24 | mA |
| I_{OL} | Low-level output current | | 24 | mA |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | 0 | 10 | ns/V |
| T_A | Operating free-air temperature | -40 | 85 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V_{CC} | $T_A = 25^\circ\text{C}$ | | | MIN | MAX | UNIT |
|--------------------------|-----------------------------------|----------|--------------------------|-----|-----|-----------|---------|---------------|
| | | | MIN | TYP | MAX | | | |
| V_{OH} | $I_{OH} = -50 \mu\text{A}$ | 4.5 V | 4.4 | | | 4.4 | V | |
| | | 5.5 V | 5.4 | | | 5.4 | | |
| | $I_{OH} = -24 \text{ mA}$ | 4.5 V | 3.94 | | | 3.8 | | |
| | | 5.5 V | 4.94 | | | 4.8 | | |
| | $I_{OH} = -75 \text{ mA}^\dagger$ | 5.5 V | | | | 3.85 | | |
| V_{OL} | $I_{OL} = 50 \mu\text{A}$ | 4.5 V | | | | 0.1 | V | |
| | | 5.5 V | | | | 0.1 | | |
| | $I_{OL} = 24 \text{ mA}$ | 4.5 V | | | | 0.36 | | |
| | | 5.5 V | | | | 0.36 | | |
| | $I_{OL} = 75 \text{ mA}^\dagger$ | 5.5 V | | | | 1.65 | | |
| I_I | $V_I = V_{CC}$ or GND | 5.5 V | | | | ± 0.1 | ± 1 | μA |
| I_{CC} | $V_I = V_{CC}$ or GND, $I_O = 0$ | 5.5 V | | | | 4 | 40 | μA |
| ΔI_{CC}^\ddagger | $V_I = V_{CC}$ or GND | 5.5 V | | | | 0.9 | 1 | mA |
| C_i | $V_I = V_{CC}$ or GND | 5 V | 3.5 | | | | | pF |

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡] This parameter is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC} .

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

| | | $T_A = 25^\circ\text{C}$ | | MIN | MAX | UNIT |
|--------------------|------------------------------------|---|-----|-----|-----|------|
| | | MIN | MAX | | | |
| f_{clock} | Clock frequency | 125 | | 125 | | MHz |
| t_w | Pulse duration | $\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low | 4 | 4 | | ns |
| | | CLK high or low | 4 | 4 | | |
| t_{su} | Setup time before CLK \downarrow | Data high or low | 3.5 | 4.5 | | ns |
| | | $\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive | 2 | 2 | | |
| t_h | Hold time after CLK \downarrow | 1.5 | 1.5 | 1.5 | | ns |

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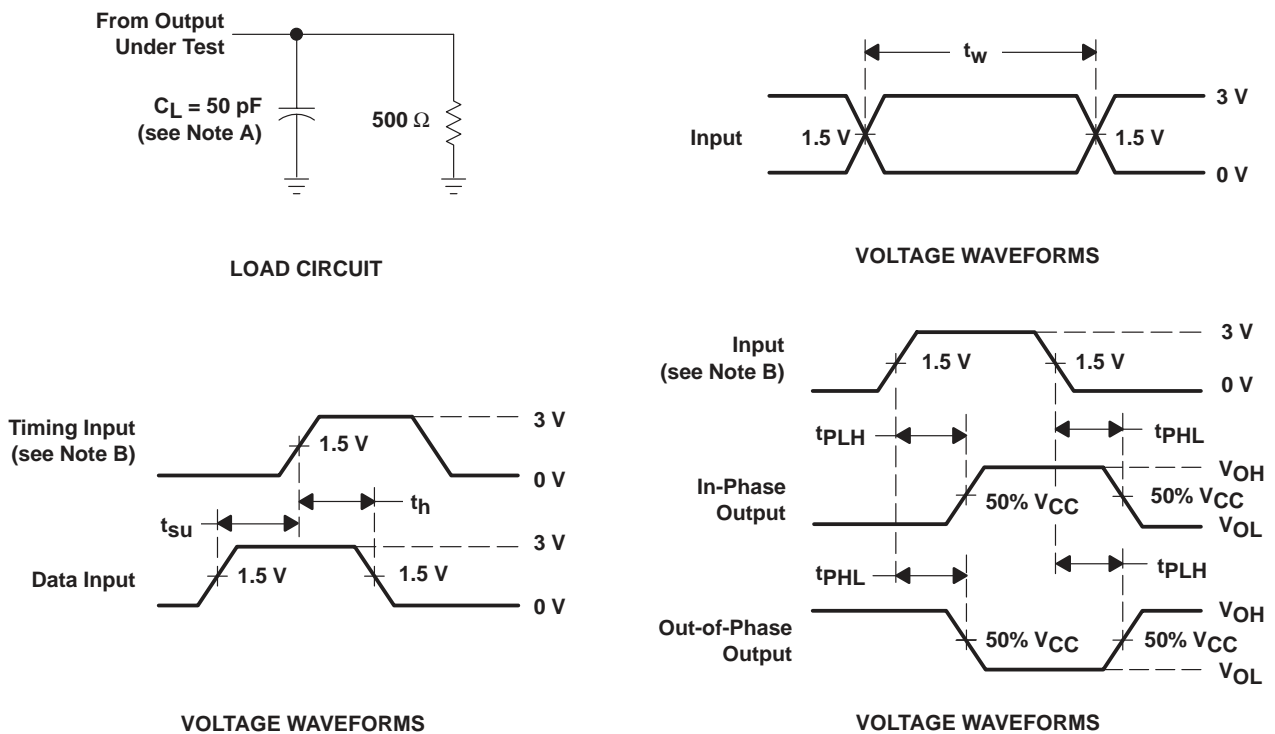
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | T _A = 25°C | | | MIN | MAX | UNIT |
|------------------|--------------|-------------|-----------------------|-----|-----|-----|-----|------|
| | | | MIN | TYP | MAX | | | |
| f _{max} | | | 125 | | | 125 | | MHz |
| t _{PLH} | PRE or CLR | Q or Q̄ | 1.5 | 3.6 | 6.3 | 1.5 | 6.8 | ns |
| t _{PHL} | | | 1.5 | 4.6 | 7.4 | 1.5 | 8 | |
| t _{PLH} | CLK | Q or Q̄ | 1.5 | 4.2 | 7 | 1.5 | 7.7 | ns |
| t _{PHL} | | | 1.5 | 4.7 | 7.4 | 1.5 | 8.4 | |

operating characteristics, V_{CC} = 5 V, T_A = 25°C

| PARAMETER | TEST CONDITIONS | TYP | UNIT |
|---|-----------------------------------|-----|------|
| C _{pd} Power dissipation capacitance per flip-flop | C _L = 50 pF, f = 1 MHz | 39 | pF |

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.

C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 74ACT11112D | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI |
| 74ACT11112DR | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI |
| 74ACT11112N | OBSOLETE | PDIP | N | 16 | | TBD | Call TI | Call TI |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

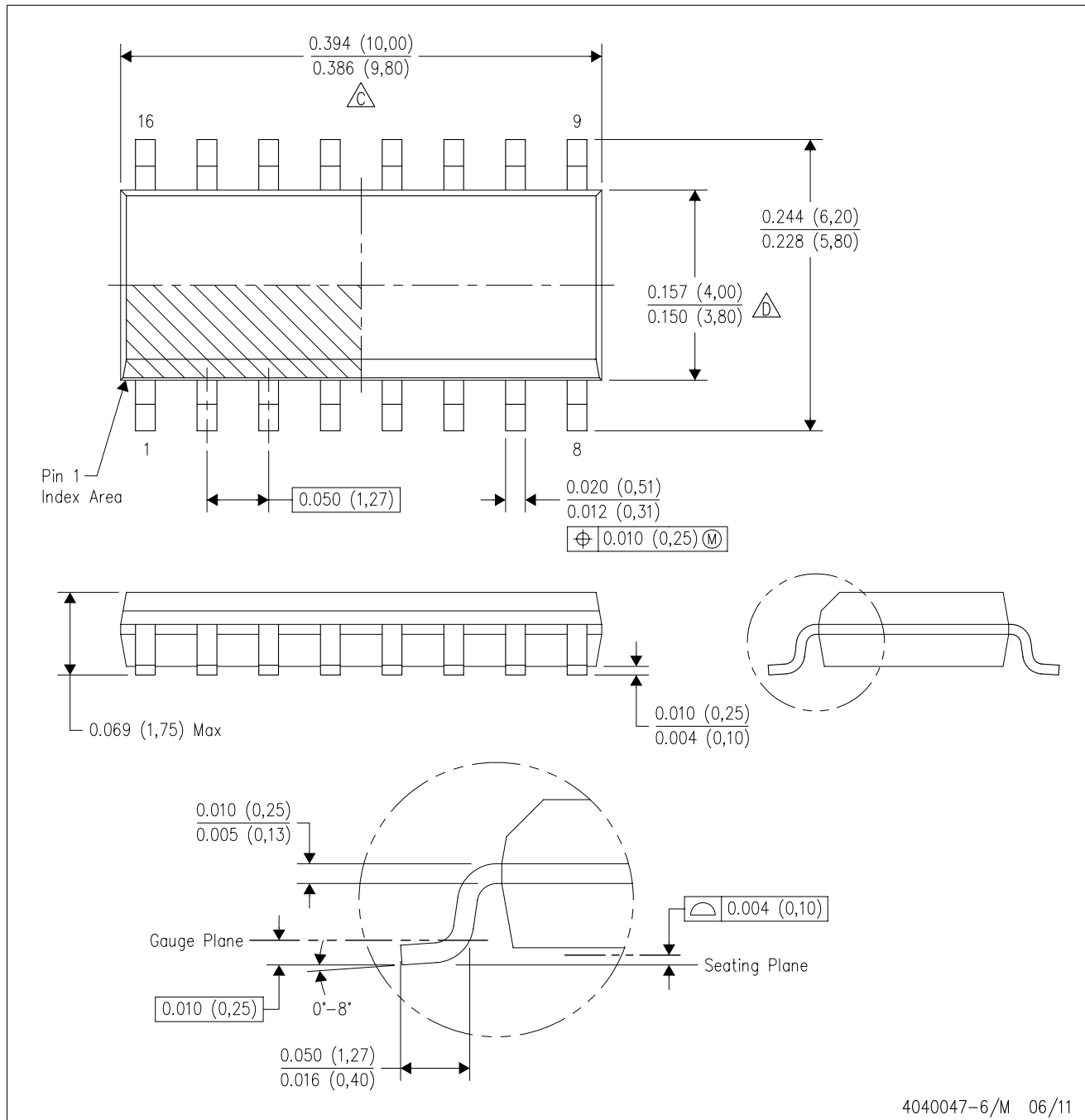
16 PINS SHOWN





- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

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